Silicon P-Channel MOS FET

HITACHI

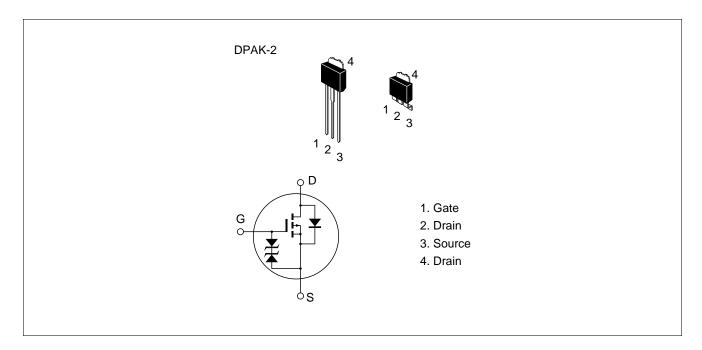
Application

High speed power switching

Features

- Low on-resistance
- Low drive current
- 2.5 V Gate drive device can be driven from 3 V Source
- Suitable for Switching regulator, DC DC converter

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

| Item | Symbol | Ratings | Unit |
|---|--------------------------|-------------|------|
| Drain to source voltage | V _{DSS} | -20 | V |
| Gate to source voltage | V _{GSS} | ±10 | V |
| Drain current | I _D | -10 | А |
| Drain peak current | L _{D(pulse)} *1 | -40 | А |
| Body to drain diode reverse drain current | I _{DR} | -10 | А |
| Channel dissipation | Pch*2 | 20 | W |
| Channel temperature | Tch | 150 | °C |
| Storage temperature | Tstg | -55 to +150 | °C |

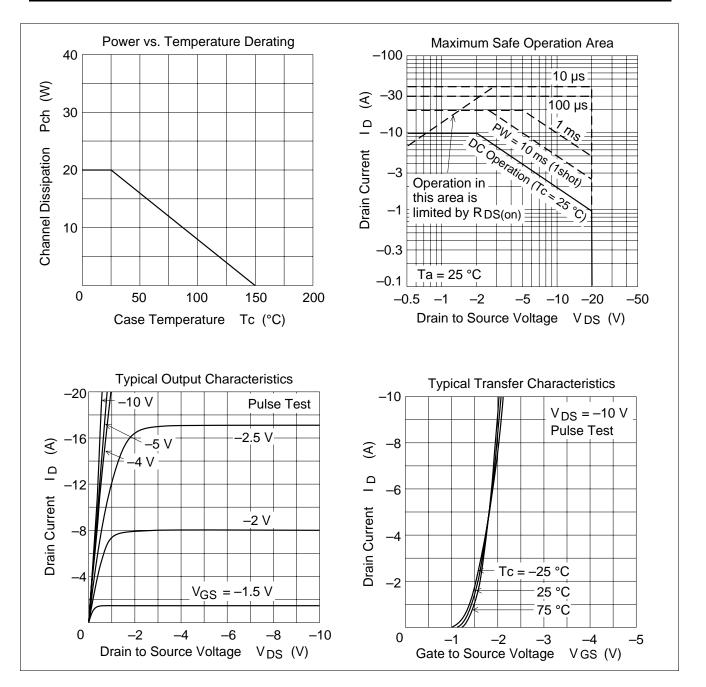
Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1 \ \%$

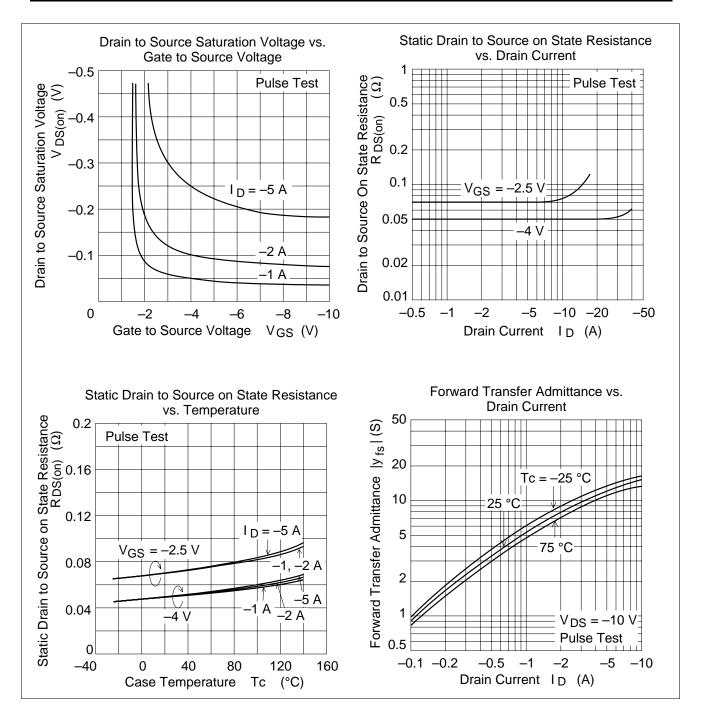
2. Value at Tc = 25°C

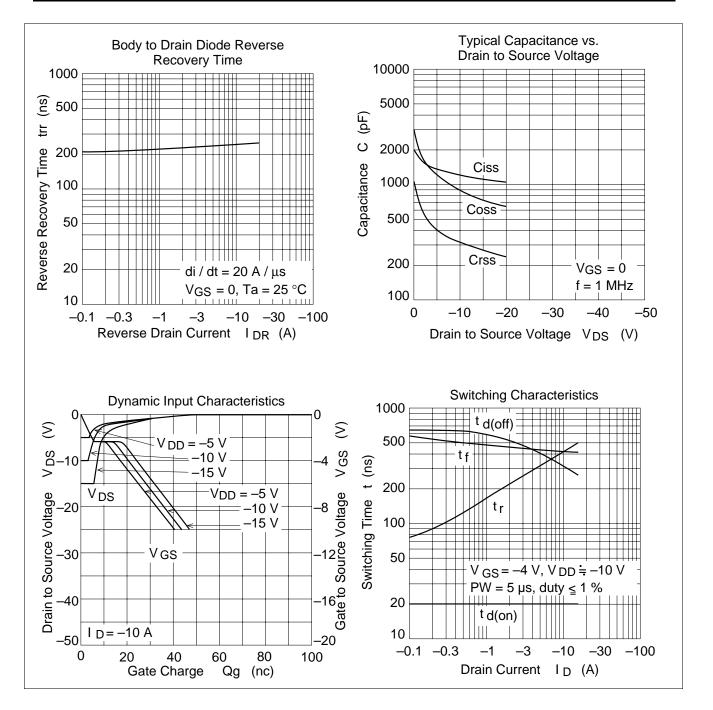
Electrical Characteristics (Ta = 25°C)

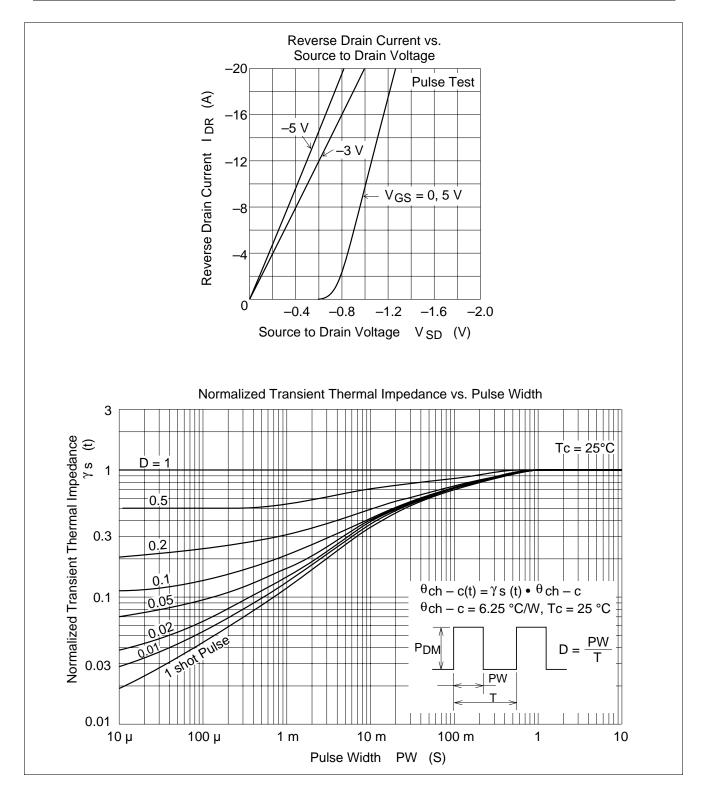
| Item | Symbol | Min | Тур | Max | Unit | Test conditions |
|--|-----------------------------|------|------|------|------|--|
| Drain to source breakdown voltage | $V_{(\text{BR})\text{DSS}}$ | -20 | _ | _ | V | $I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$ |
| Gate to source breakdown voltage | $V_{(BR)GSS}$ | ±10 | _ | _ | V | $I_{g} = \pm 200 \ \mu A, \ V_{DS} = 0$ |
| Gate to source leak current | I _{GSS} | | _ | ±10 | μΑ | $V_{GS} = \pm 6.5 \text{ V}, V_{DS} = 0$ |
| Zero gate voltage drain current | I _{DSS} | | _ | -100 | μΑ | $V_{\rm DS} = -16 \rm V, V_{\rm GS} = 0$ |
| Gate to source cutoff voltage | $V_{GS(off)}$ | -0.5 | — | -1.5 | V | $I_{\rm D} = -1 \text{ mA}, V_{\rm DS} = -10 \text{ V}$ |
| Static drain to source on state resistance | $R_{DS(on)}$ | — | 0.05 | 0.07 | Ω | $I_{\rm D} = -5 \text{ A}$ $V_{\rm GS} = -4 \text{ V}^{*1}$ |
| | | — | 0.07 | 0.1 | Ω | $I_{\rm D} = -5 \text{ A}$ $V_{\rm GS} = -2.5 \text{ V}^{*1}$ |
| Forward transfer admittance | y _{fs} | 7 | 12 | — | S | $I_{D} = -5 \text{ A}$ $V_{DS} = -10 \text{ V}^{*1}$ |
| Input capacitance | Ciss | _ | 1170 | — | pF | $V_{\rm DS} = -10 \ V$ |
| Output capacitance | Coss | | 860 | _ | pF | $V_{GS} = 0$ |
| Reverse transfer capacitance | Crss | _ | 310 | — | pF | f = 1 MHz |
| Turn-on delay time | t _{d(on)} | | 20 | _ | ns | I _D = -5 A |
| Rise time | t, | | 325 | _ | ns | $V_{GS} = -4 V$ |
| Turn-off delay time | $t_{d(off)}$ | | 350 | _ | ns | $R_{L} = 2 \Omega$ |
| Fall time | t _f | _ | 425 | _ | ns | |
| Body to drain diode forward voltage | V_{DF} | — | -1.0 | — | V | $I_{\rm F} = -10$ A, $V_{\rm GS} = 0$ |
| Body to drain diode reverse recovery time | t _{rr} | _ | 240 | — | ns | $I_F = -10 \text{ A}, V_{GS} = 0,$ diF/dt = 20 A/µs |

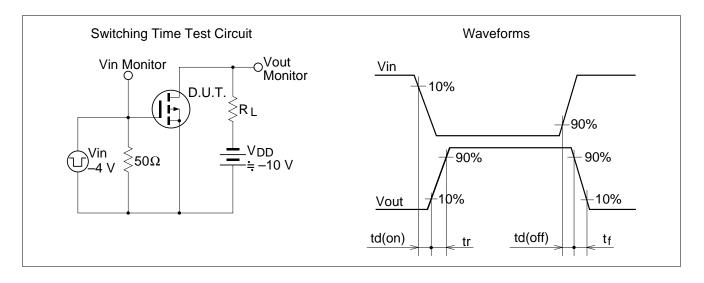
Note: 1. Pulse Test



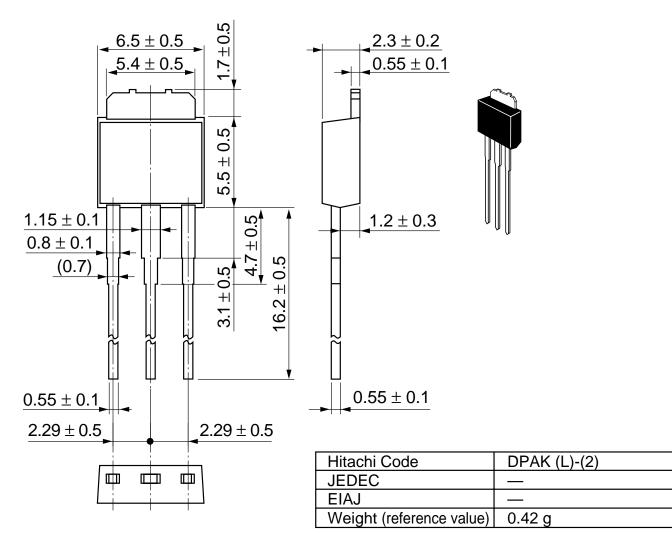








Unit: mm



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